

APPLICATION DATA SHEET**Inventor Information**

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Application Information

Title : METHOD OF PRESSURE CURING FOR REDUCING
VOIDS IN A DIE ATTACH BONDLINE AND
APPLICATIONS THEREOF
Total Drawing Sheets : 2
Formal Drawings : YES
Application Type : Utility
Attorney Docket Number : 500180.03 (29249/US/2)
Assigned : Yes (Large Entity)

Representative Information

Representative Customer No. : 27,076

Continuity Information

This application is a	:	continuation of
>Application One	:	09/895,662
Filing Date	:	June 29, 2001
which is a	:	divisional of
>>Application Two	:	09/515,579
Filing Date	:	February 29, 2000
Patent Number	:	6,524,891

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